



US 20240237291A1

(19) **United States**

(12) **Patent Application Publication**  
**CHANG**

(10) **Pub. No.: US 2024/0237291 A1**

(43) **Pub. Date: Jul. 11, 2024**

(54) **MODULE SOCKET ASSEMBLY WITH AIR DUCT**

**Publication Classification**

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(51) **Int. Cl.**  
**H05K 7/20** (2006.01)

(52) **U.S. Cl.**  
CPC ..... **H05K 7/2039** (2013.01)

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(57) **ABSTRACT**

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A module socket assembly with an air duct includes a module socket including a circuit board and a front panel disposed on a side of the circuit board. A module casing is disposed on the circuit board. A front end of the module casing has a module jack and passes through a module casing opening of the front panel. The front panel has an air duct opening. An air duct covers the module casing, passes through the air duct opening, and has an air duct body. An air passage extending in a front-rear direction is formed inside the air duct body. With the air duct, the present disclosure allows an air current entering from a front end of the air duct to concentratedly pass through a heat sink of the module casing, thereby preventing dissipation of the air current.

(21) Appl. No.: **18/542,796**

(22) Filed: **Dec. 18, 2023**

**Related U.S. Application Data**

(60) Provisional application No. 63/437,233, filed on Jan. 5, 2023.

